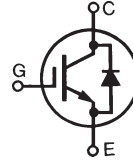


# GenX3™ 600V IGBT w/ Diode

# IXGK72N60B3H1 IXGX72N60B3H1

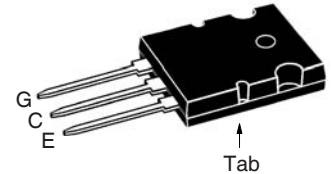
Medium Speed Low V<sub>sat</sub> PT  
IGBTs 5-40 kHz Switching



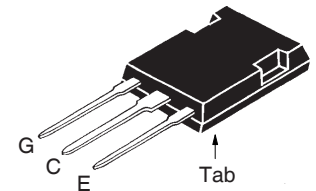
$V_{CES} = 600V$   
 $I_{C110} = 72A$   
 $V_{CE(sat)} \leq 1.8V$   
 $t_{fi(typ)} = 92ns$

Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ C$ to $150^\circ C$	600	V
$V_{CGR}$	$T_J = 25^\circ C$ to $150^\circ C$ , $R_{GE} = 1M\Omega$	600	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ C$ ( Chip Capability)	178	A
$I_{LRMS}$	Terminal Current Limit	160	A
$I_{C110}$	$T_C = 110^\circ C$	72	A
$I_{CM}$	$T_C = 25^\circ C$ , 1ms	450	A
<b>SSOA</b> <b>(RBSOA)</b>	$V_{GE} = 15V$ , $T_{VJ} = 125^\circ C$ , $R_G = 3\Omega$ Clamped Inductive Load	$I_{CM} = 240$ @ $V_{CE} \leq V_{CES}$	A
$P_C$	$T_C = 25^\circ C$	540	W
$T_J$		-55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		-55 ... +150	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ C$
$T_{SOLD}$	1.6 mm (0.062in.) from Case for 10s	260	$^\circ C$
$M_d$	Mounting Torque (TO-264)	1.13/10	Nm/lb.in
$F_C$	Mounting Force (PLUS247)	20..120 /4.5..27	N/lb
<b>Weight</b>	TO-264	10	g
	PLUS247	6	g

TO-264 (IXGK)



PLUS247 (IXGX)



G = Gate                      E = Emitter  
 C = Collector                Tab = Collector

## Features

- Optimized for Low Conduction and Switching Losses
- Square RBSOA
- Anti-Parallel Ultra Fast Diode

## Advantages

- High Power Density
- Low Gate Drive Requirement

## Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions ( $T_J = 25^\circ C$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$V_{GE(th)}$	$I_C = 250\mu A$ , $V_{CE} = V_{GE}$	3.0		5.0 V
$I_{CES}$	$V_{CE} = V_{CES}$ , $V_{GE} = 0V$ $T_J = 150^\circ C$			300 $\mu A$ 5 mA
$I_{GES}$	$V_{CE} = 0V$ , $V_{GE} = \pm 20V$			$\pm 100$ nA
$V_{CE(sat)}$	$I_C = 60A$ , $V_{GE} = 15V$ , Note 1 $I_C = 120A$	1.50	1.75	V V

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values			
		Min.	Typ.	Max.	
$g_{fs}$	$I_C = 50\text{A}$ , $V_{CE} = 10\text{V}$ , Note 1	45	76	S	
$C_{ies}$	$V_{CE} = 25\text{V}$ , $V_{GE} = 0\text{V}$ , $f = 1\text{MHz}$		6800	pF	
$C_{oes}$			575	pF	
$C_{res}$			80	pF	
$Q_{g(on)}$	$I_C = 60\text{A}$ , $V_{GE} = 15\text{V}$ , $V_{CE} = 0.5 \cdot V_{CES}$		225	nC	
$Q_{ge}$			40	nC	
$Q_{gc}$			82	nC	
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b> $I_C = 50\text{A}$ , $V_{GE} = 15\text{V}$ $V_{CE} = 480\text{V}$ , $R_G = 3\Omega$ Note 2		31	ns	
$t_{ri}$			33	ns	
$E_{on}$			1.4	mJ	
$t_{d(off)}$			152	240	ns
$t_{fi}$			92	150	ns
$E_{off}$			1.0	2.0	mJ
$t_{d(on)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b> $I_C = 50\text{A}$ , $V_{GE} = 15\text{V}$ $V_{CE} = 480\text{V}$ , $R_G = 3\Omega$ Note 2		29	ns	
$t_{ri}$			34	ns	
$E_{on}$			2.7	mJ	
$t_{d(off)}$			228	ns	
$t_{fi}$			142	ns	
$E_{off}$			2.2	mJ	
$R_{thJC}$			0.23	$^\circ\text{C/W}$	
$R_{thCS}$		0.15		$^\circ\text{C/W}$	

### Reverse Diode (FRED)

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$V_F$	$I_F = 60\text{A}$ , $V_{GE} = 0\text{V}$ , Note 1			2.45 V
		$T_J = 150^\circ\text{C}$	1.40	1.80 V
$I_{RM}$	$I_F = 60\text{A}$ , $V_{GE} = 0\text{V}$ , $-di_F/dt = 200\text{A}/\mu\text{s}$ , $V_R = 300\text{V}$	$T_J = 100^\circ\text{C}$	8.3	A
$t_{rr}$			140	ns
$R_{thJC}$			0.30	$^\circ\text{C/W}$

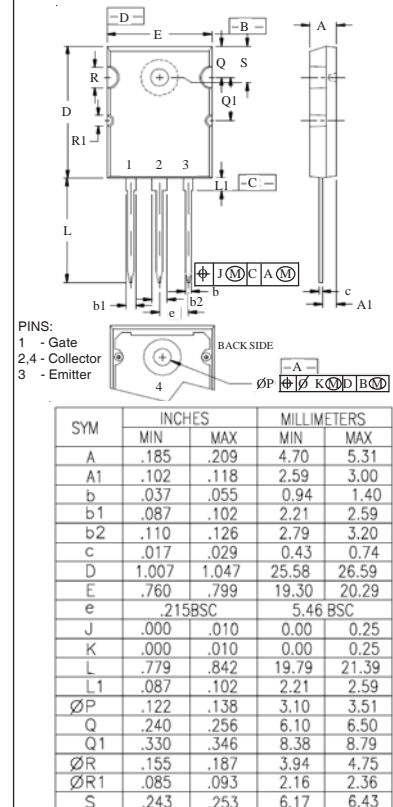
### Notes:

1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .
2. Switching times & energy losses may increase for higher  $V_{CE}$  (Clamp),  $T_J$  or  $R_G$ .

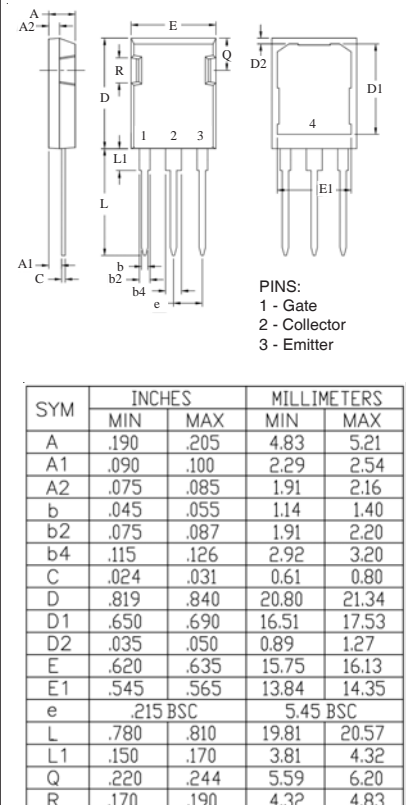
IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

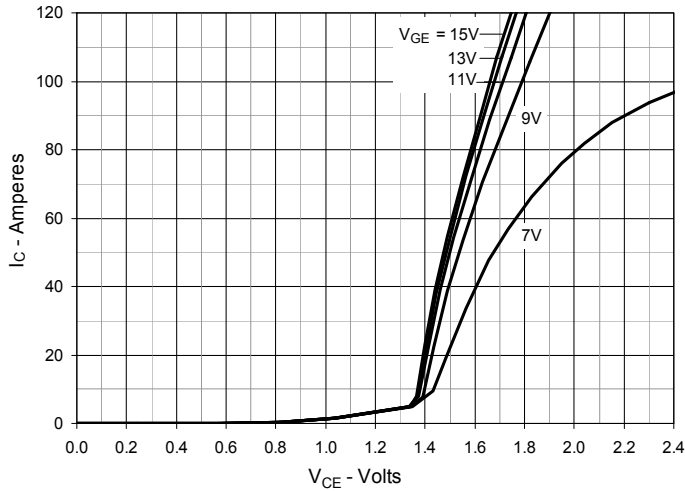
### TO-264 Outline



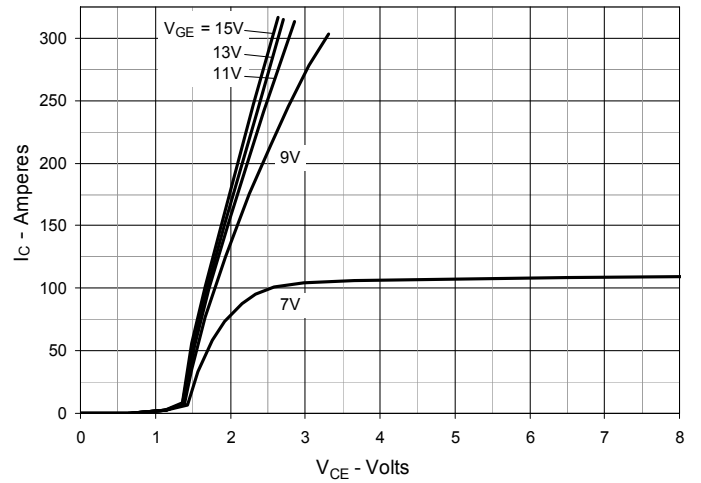
### PLUS247™ Outline



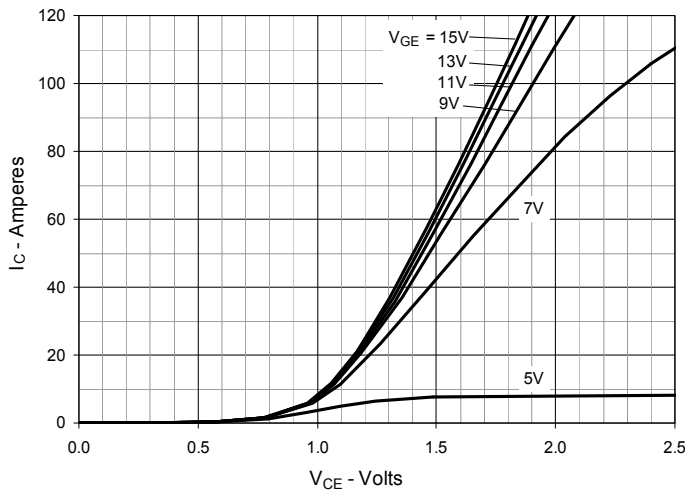
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$**



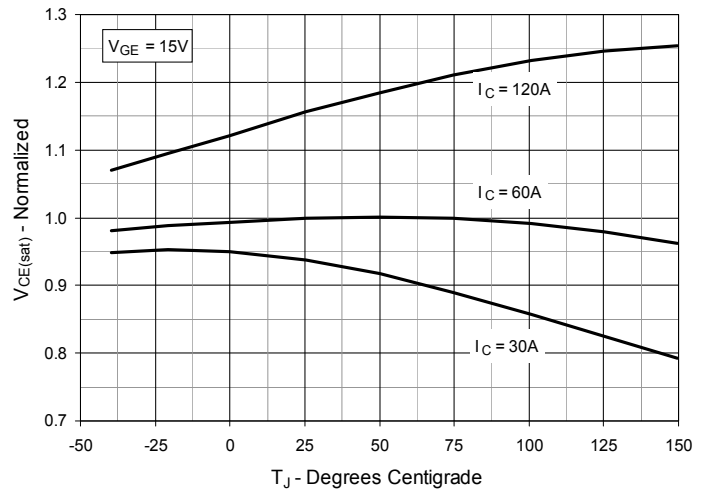
**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$**



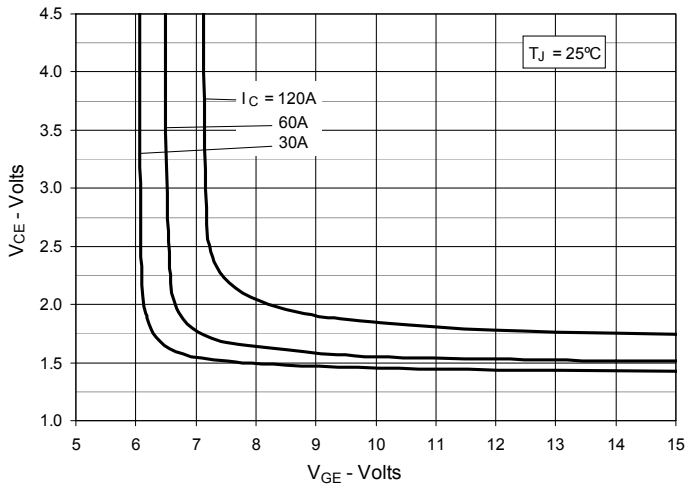
**Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$**



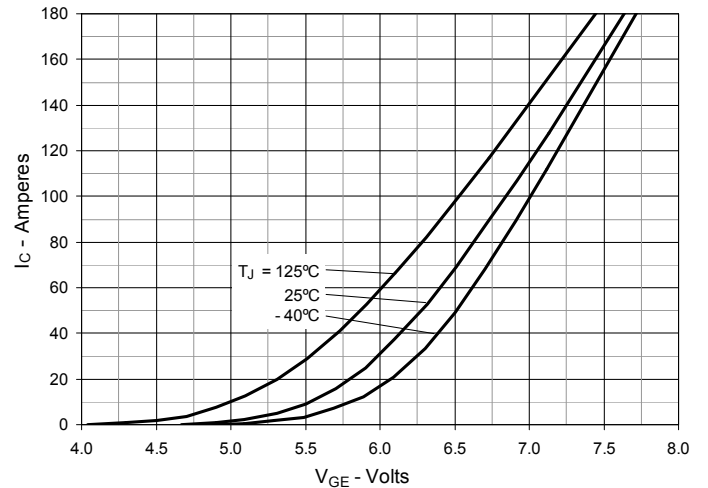
**Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature**



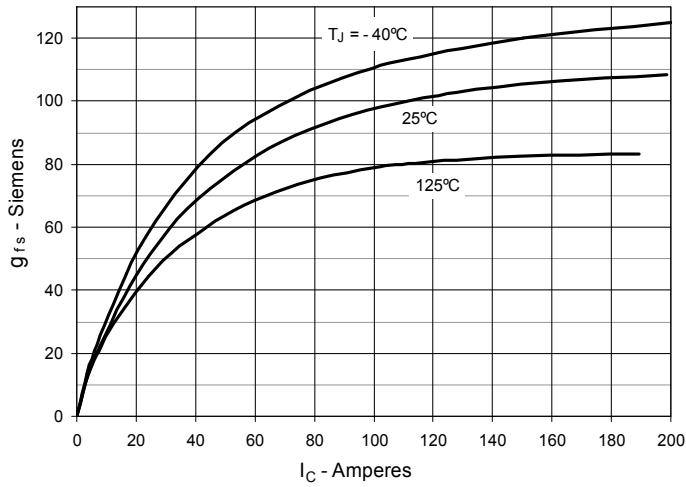
**Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**



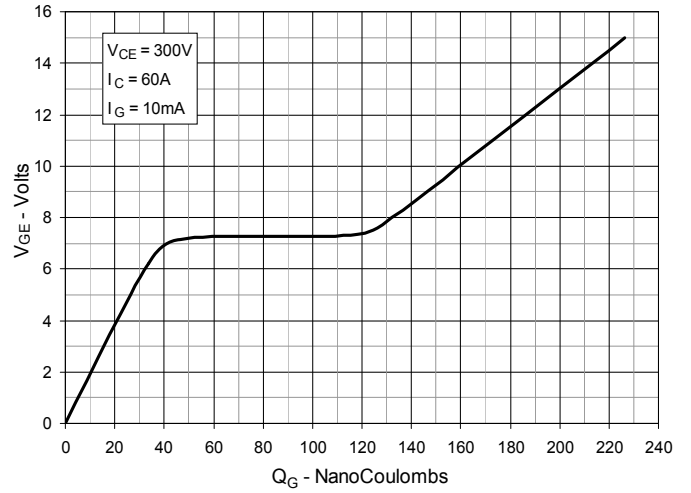
**Fig. 6. Input Admittance**



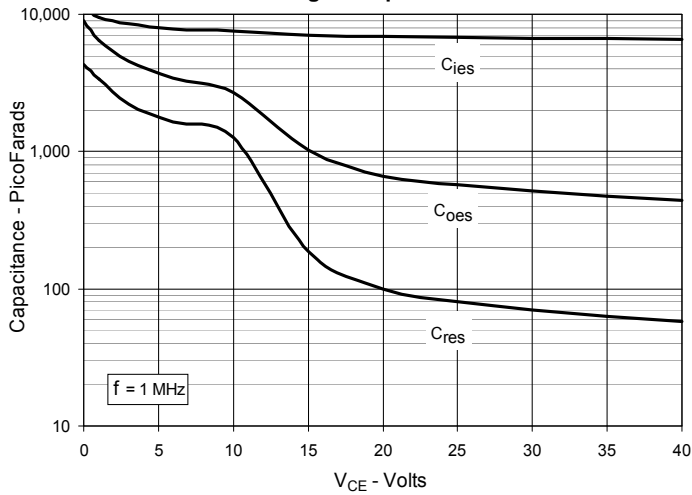
**Fig. 7. Transconductance**



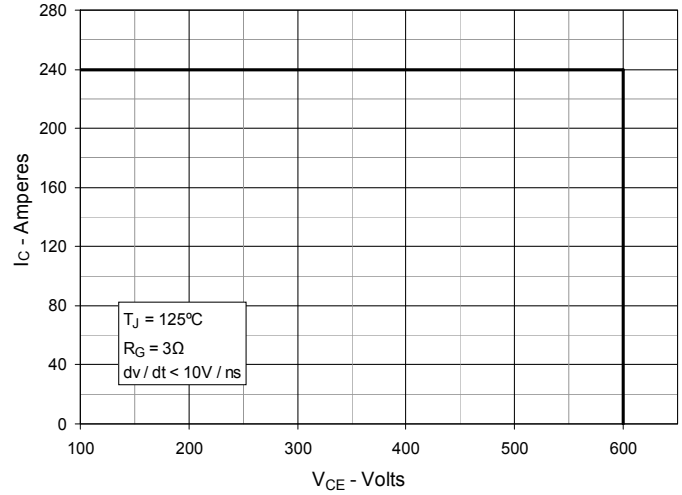
**Fig. 8. Gate Charge**



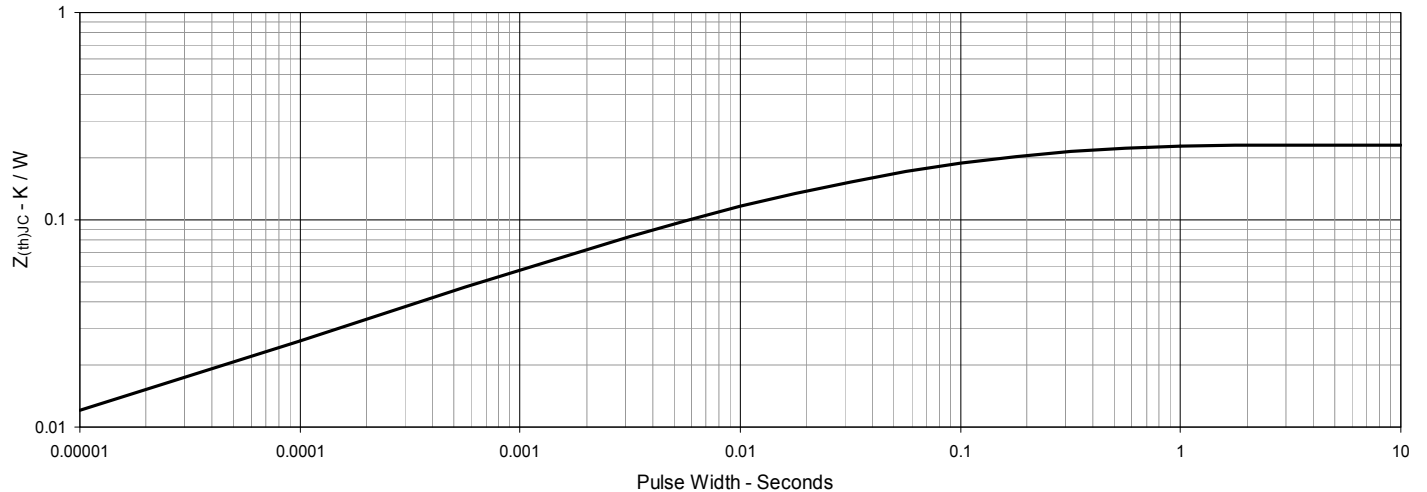
**Fig. 9. Capacitance**



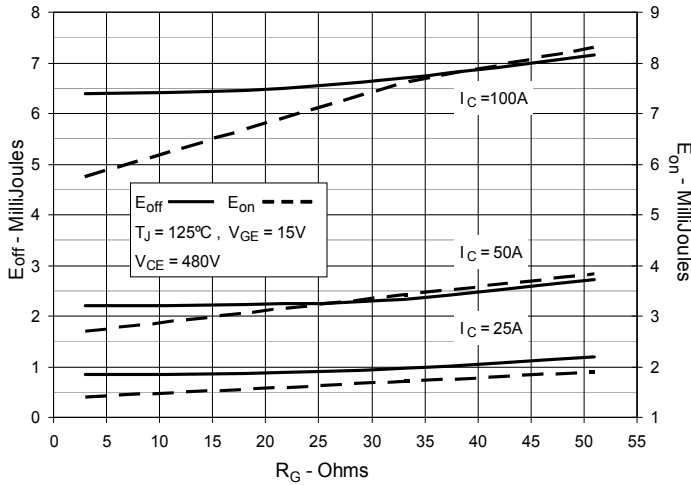
**Fig. 10. Reverse-Bias Safe Operating Area**



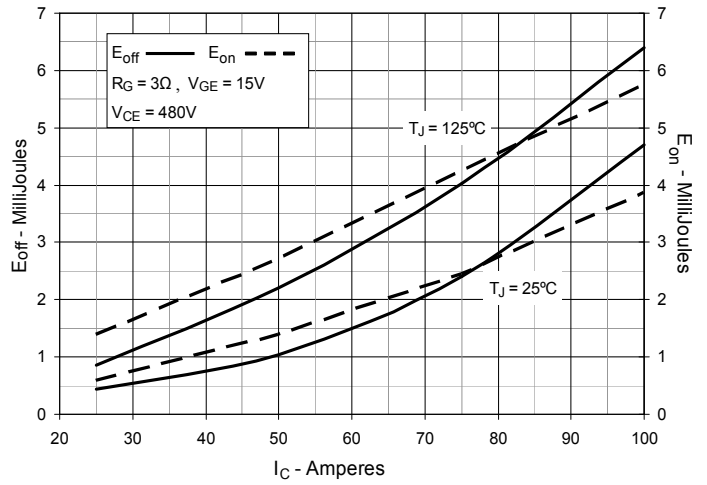
**Fig. 11. Maximum Transient Thermal Impedance for IGBT**



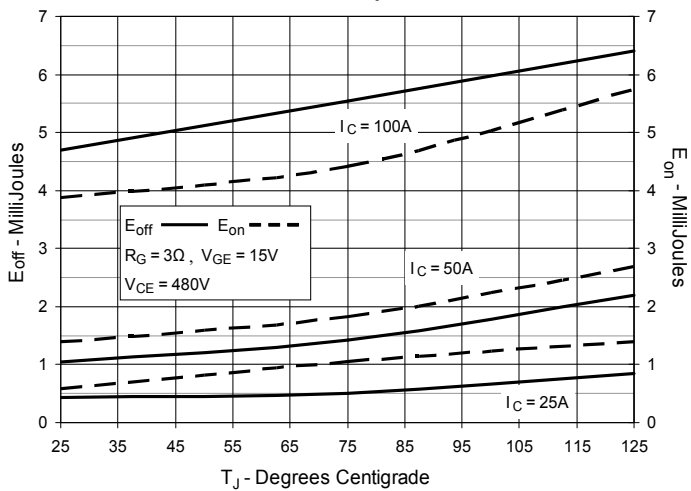
**Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance**



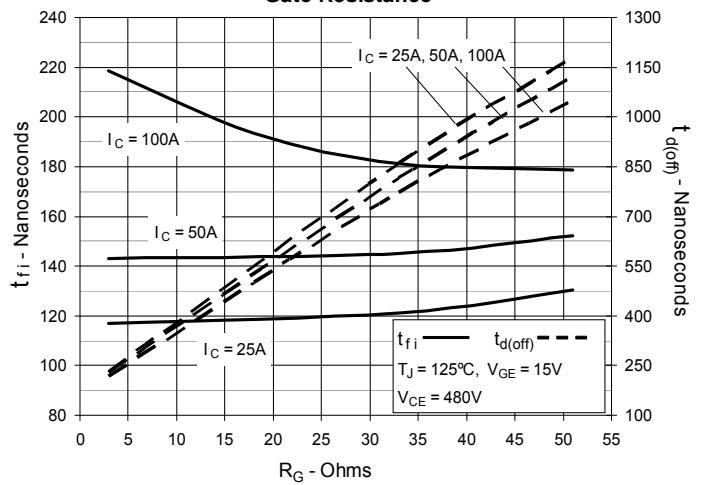
**Fig. 13. Inductive Switching Energy Loss vs. Collector Current**



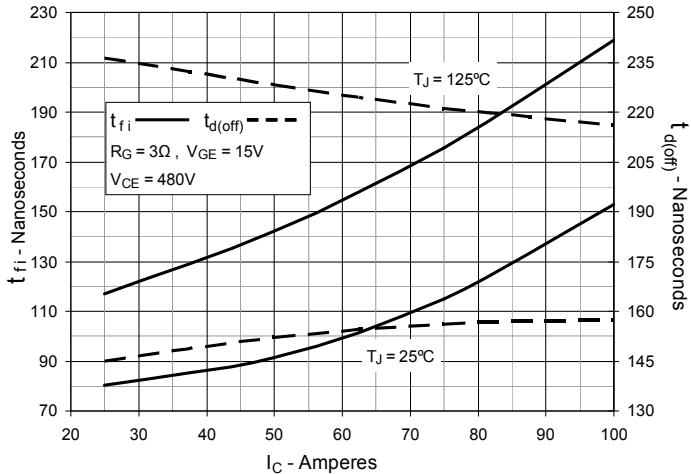
**Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature**



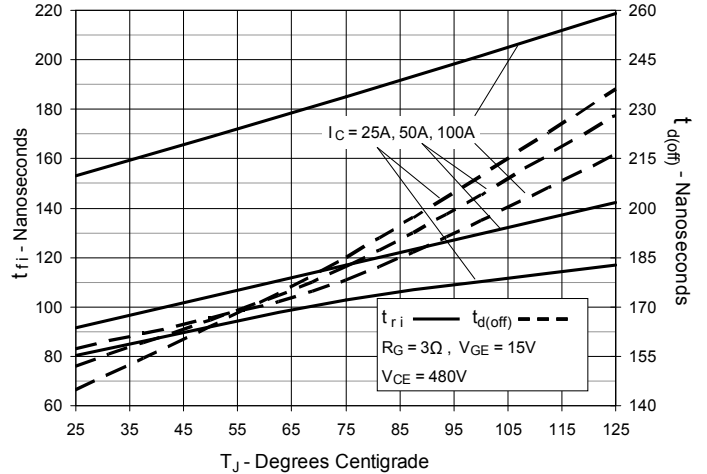
**Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance**



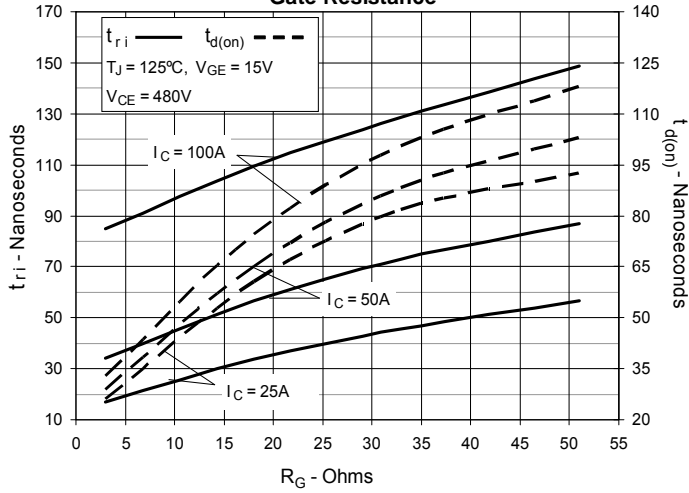
**Fig. 16. Inductive Turn-off Switching Times vs. Collector Current**



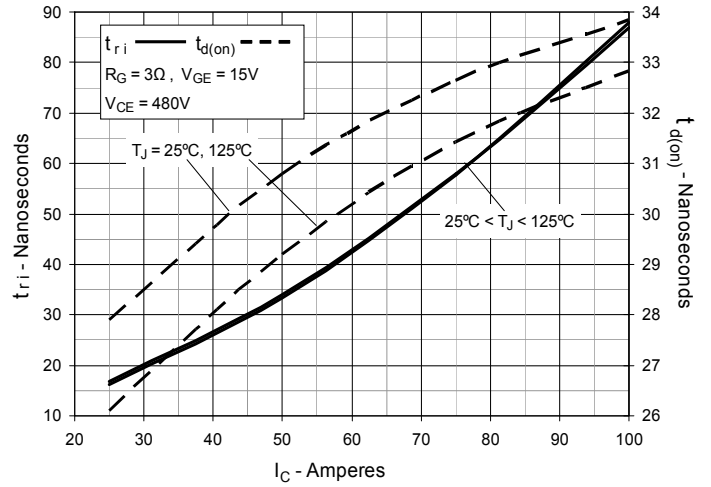
**Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature**



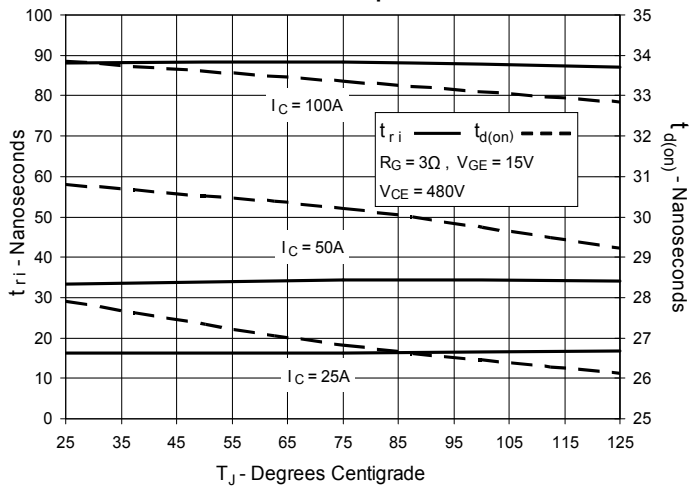
**Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance**



**Fig. 19. Inductive Turn-on Switching Times vs. Collector Current**



**Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature**



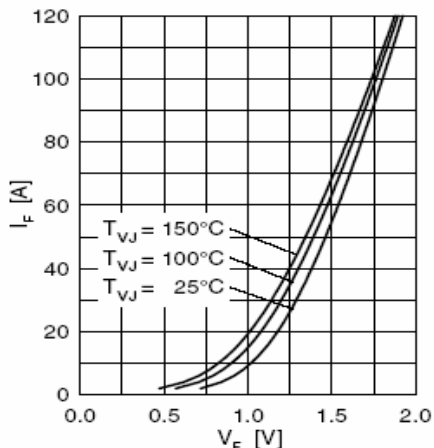


Fig. 21 Forward current  $I_F$  vs.  $V_F$

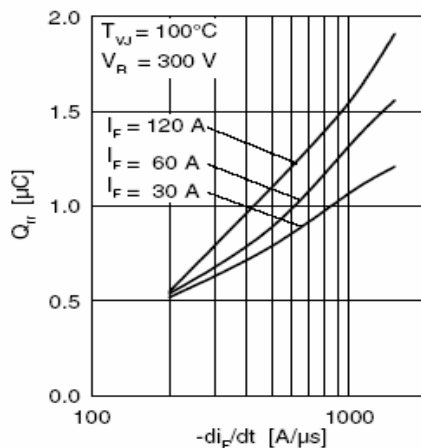


Fig. 22 Typ. reverse recovery charge  $Q_{rr}$

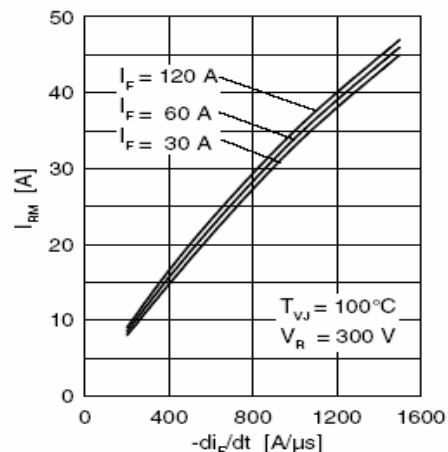


Fig. 23 Typ. peak reverse current  $I_{RM}$

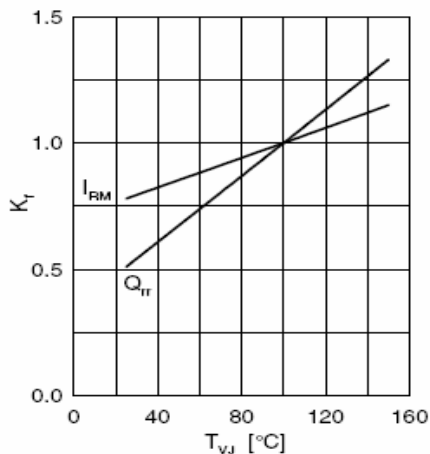


Fig. 24 Typ. dynamic parameters  $Q_{rr}$ ,  $I_{RM}$

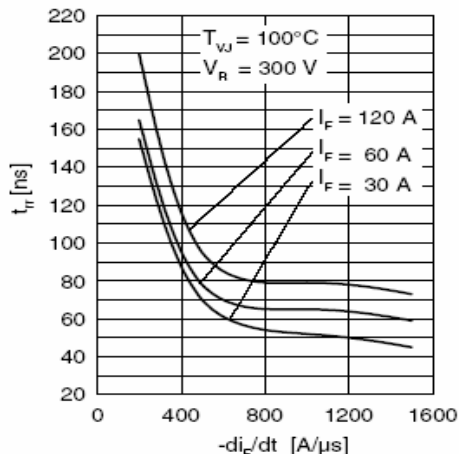


Fig. 25 Typ. recovery time  $t_{rr}$

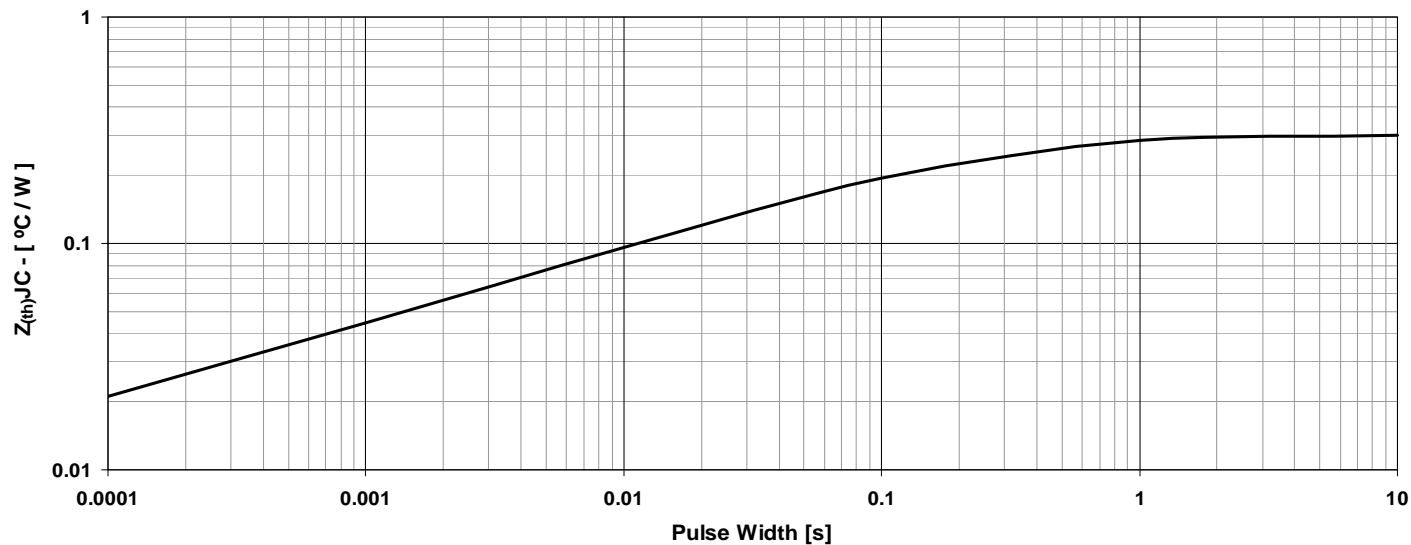


Fig. 26 Maximum Transient Thermal Impedance Junction to Case (for Diode)